	L Number	Hits	Search Text	DB	Time stamp
•	1	92	ceramic adj capacitor and laminated near b dy and baking	USPAT; US-PGPUB; EP ; JPO; DERWENT;	2004/03/02 11:56
	2	2	6349026.pn.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/03/02 11:49
4,	3	0	6349026.URPN.	DERWENT; IBM_TDB USPAT	2004/03/02 11:49
2	4	0	6349026.URPN.	USPAT	2004/03/02
k	5	6	capacitor and laminated near body and baking and common adj material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/02 12:20
78	V 6	. 6	("4982485" "5426560" "5822176" "5841626" "5995360" "6002577").PN.	USPAT	2004/03/02 11:57
J. C.	3 7 3	7	("4574329" "4610971" "4985381" "5036424" "5117326" "5659456" "5734545").PN.	USPAT	2004/03/02 12:04
St.	8	6	("3237066" "3679950" "3720862" "3879645" "3902102" "4447853").PN.	USPAT	2004/03/02 12:17
	9	18	ceramic adj capacitor and laminated near body and baking and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/02 12:21
	10	17	ceramic adj capacitor and laminated near body and baking and (29/25.42, 29/25.41, 29/831, 29/846).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/02 12:23
	.11	36	ceramic adj capacitor and laminated near body and baking and (29/25.42; 29/611; 29/612; 29/25.41; 29/830; 361/321.2; 361/321.4; 361/321.5; 361/303; 501/32; 501/136; 501/137).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/02 12:38
:	12	7	("5731950" "5742473" "5801111" "5815368" "5822176" "5835340" "5862034").PN.	USPAT	2004/03/02 12:29
-	13	4	ceramic adj capacitor and laminated near body and inner adj electrodes and external near electr des and baking and (29/25.42; 29/611; 29/612; 29/25.41; 29/830; 361/321.2; 361/321.4; 361/321.5; 361/303; 501/32; 501/136; 501/137).ccls.	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2004/03/02 12:43

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14	0	unbaked near ceramic adj capacit r and	USPAT;	2004/03/02
		laminated near body and inner adj	US-PGPUB;	12:44
		electrodes and external near electrodes	EP ; JP ;	
		and baking and (29/25.42; 29/611 ; 29/612 ;	DERWENT;	-
		29/25.41 ; 29/830 ; 361/321.2 ; 361/321.4 ;	IBM_TDB	
		361/321.5 ; 361/303 ; 501/32 ; 501/136 ;		
		501/137).ccls.		
15	0	unbaked near ceramic and laminated near	USPAT;	2004/03/02
		body and inner adj electrodes and external	US-PGPUB;	12:44
		and baking	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	6	unbaked near ceramic and laminated near	USPAT;	2004/03/02
		body and baking	US-PGPUB;	12:47
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	6	3090987.URPN.	USPAT	2004/03/02
				12:46
18	2	5600101.pn.	USPAT;	2004/03/02
			US-PGPUB;	12:54
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
19	1	1996-148778.NRAN.	DERWENT	2004/03/02
				12:48
20	2	5181044.pn.	USPAT;	2004/03/02
			US-PGPUB;	12:54
			EPO; JPO;	
			DERWENT;	
			IBM TDB	l

	Titl	Current OR	Current XR f	Retrieval Clas if
-	M thod of producing electronic parts, and m mber for production thereof	29/846		29/846
N	M th d of forming an electronic c mponent using ink	347/44	29/830; 29/831; 29/846; 29/890.1; 347/20	29/831; 29/846
၉	Multilayer ceramic electronic components and methods for manufacturing the same	29/25.42	29/25.41; 29/831; 29/846	29/25.41; 29/25.42; 29/831; 29/846
4	M th d of forming an electronic c mponent using ink	29/890.1	252/62.51R; 29/830; 29/831; 29/852; 427/190; 427/201; 427/205; 427/96;	29/831
2	M th d of producing a monolithic ceramic capacitor	29/25.42	29/25.41; 29/830; 501/136; 501/32	29/25.41; 29/25.42
9	M th d for manufacturing a multilayered ceramic electronic component	432/17	29/25.42; 432/121	29/25.42

	1 141	Curr nt OR	Current XRef	Retri val Classif
7	Multilayer ceramic capacitor	361/306.3	29/25.42; 361/303; 361/306.1; 361/310; 361/321.2	29/25.42
8	El ctronic component having external el ctrodes and method for the manufacture thereof	361/308.1	29/25.41; 361/309; 361/321.2	29/25.41
6	Laminated ceramic electronic part including a plurality of internal electrodes having two leading portions and a n n-xposed portion between the two I ading portions	361/303	257/E21.53; 29/25.42; 361/306.3; 361/313	29/25.42
10	Laminated capacitor and trimming method 361/303	361/303	29/25.42; 361/306.1; 361/306.3; 361/309; 361/329	29/25.42
7	C ramic capacitor with a grain b undary-insulated structure	29/25.03	252/513; 252/514; 252/519.12; 29/25.42; 361/311; 361/321.5	29/25.42
12	C ramic capacitor and method for the pr paration thereof	361/321.5	29/25.42	29/25.42

	Tit	Curr nt OR	Current XRef	R tri val Classif
13	S miconductor-type laminated ceramic capacitor with a grain boundary-insulated structure and a method for producing the same	361/321.4	29/25.42; 501/135	29/25.42
14	Laminated semiconductor ceramic capacitor with a grain boundary-insulated structure and a method for producing the same	361/321.5	156/89.16; 252/519.12; 29/25.42	29/25.42
15	Multilayer capacitor and method of fabricating the same	361/321.2	29/25.42; 361/309	29/25.42
16	S miconductor-type laminated ceramic capacitor with a grain boundary-insulated structure and a method for producing the sam	361/321.4	29/25.42 ; 501/135	29/25.42
17	High-voltage ceramic capacitor and m thod of producing the same	361/321.2	29/25.42 ; 361/328	29/25.42